

# Amphenol® High Density HDB<sup>3</sup> and HSB<sup>3</sup> Connector Series

SL-402-1

**HDB<sup>3</sup>**  
High Density



**Amphenol**  
Aerospace

# TABLE OF CONTENTS

Page No.

Performance/Features	1
HDB <sup>3</sup> Mother Board	2
HDB <sup>3</sup> Daughter Board	3
HDB <sup>3</sup> I/O Connector	4
HDB <sup>3</sup> Stacker Connector	5
HSB <sup>3</sup> High Speed Mother Board	6
HSB <sup>3</sup> High Speed Daughter Board	7
HSB <sup>3</sup> High Speed Layout	8
HSB <sup>3</sup> High Speed Recommended Board Layout for Daughter Board	9
HSB <sup>3</sup> High Speed Recommended Board Layout for Mother Board	10
Hardware for HDB <sup>3</sup> and HSB <sup>3</sup>	11
Other Amphenol Rectangular Products	12
Sales Office and Distributor Listing	13



# BRISTLE BRUSH ADVANTAGES

## The superior choice for board level interconnects

The Bristle Brush contact has been proven in military avionics packages and meets the requirements of MIL-DTL-55302. It provides high density in tighter spacing which is a main concern for integrated electronics in aircraft systems.

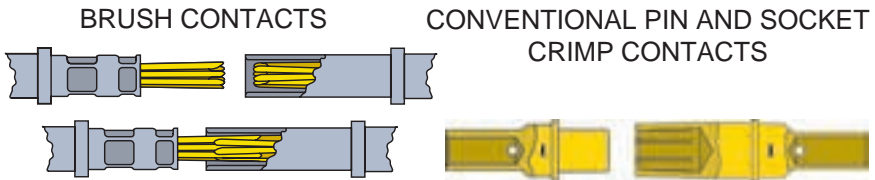
Brush vs. Conventional Contacts

### Brush Contact Innovation

- Multiple contact interfaces: Strands of high tensile strength wire are bundled together to form brush-like contacts. By intermeshing two multi-strand wire bundles, an electrical connection is made.
- Provides redundant current paths, 14-70 (point of contact) per mated contact with a gas tight junction.
- Very smooth (low friction) interface

### Conventional Pin/Socket

- Machined surface finish on both parts
- Higher friction and wear
- Limited number of contact sites



### Amphenol Brush Contact Provides:

- Low mating forces (70% to 90% lower than conventional pin and socket contacts)
- Easy mating/unmating makes high circuit counts practical (25 lbs. typical for 400 contacts)
- Multiple points of contact = superior electrical capability
  - Stable, low resistance-20milliohms max.
  - Redundant current paths
  - Proven electrical and gas tight contact sites
- Severe environment protection
- High current rating
- Long contact life (100,000 cycles of mating and unmating with out performance degradation)
- Documented intermittency-free performance - no 10 nanosecond discontinuities during 50,000,000 cycles of 0.010 displacement
- Overall cost effectiveness (life cycle cost)
- Protection against micro-arcing
- No degradation in a fretting/micro-motion environment

# HIGH DENSITY BRUSH (HDB<sup>3</sup>) SERIES

## HDB<sup>3</sup> High Density Brush Series with tighter (.070 inch X .060 inch) staggered grid spacing

This new connector series of brush connectors incorporates a higher density contact pattern and lower mated height than Amphenol's standard low mating force rectangular connectors. HDB<sup>3</sup> connectors utilize the same durable and reliable B<sup>3</sup> brush contact in a tighter .070" X .060" staggered grid pattern. They offer the advantage of higher density in a compact-height connector utilizing less board space. Styles include mother board, daughter board, input/output and stacker.

### HDB<sup>3</sup> MATERIALS

- Insulator: Liquid crystal polymer, 30% glass filled  
 Contact: Wire: Beryllium copper per ASTM B197; finish is gold per ASTM B488 over nickel per AMS-QQ-N-290.  
 Holder: Brass similar to UNS C33500; available finishes include gold per MIL-G-45204, tin-lead per MIL-P-81728 or tin per MIL-T-10727 (RoHS Compliant).  
 Sleeve: Stainless Steel per AMS-5514, passivated IAW QQ-P-35 (Daughter Board, I/O and Stacker connector)  
 Keys/Guide Pins: Stainless Steel

# COMPARISON

## COMPARISON

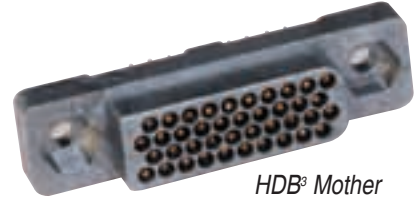
The Amphenol HDB<sup>3</sup> Connector offers advantages over competitive connectors:

- Higher density contact pattern
- Uses less board space
- Allows for shorter mated height
- Provides the durability and performance of the Brush contact
- Low cost

	Amphenol HDB <sup>3</sup>	Hypertronics HPH	Airborn RM4
Contact System	Brush	Hyperboloid	Pin & Socket
Durability, Mating Cycles	100,000	2,000	500
Contact Mating Forces, Ounces	1.5	1.5	2.5
Mother Board	.070 X .060	.075 X .075	.075 X .070
Daughter Board	.070 X .060	.075 X .100	.075 X .100
Connector Width	.350	.443	.400
Mated Height, MB to 4th row of DB	.680	.986	.915



HDB<sup>3</sup> Daughter Board Connector



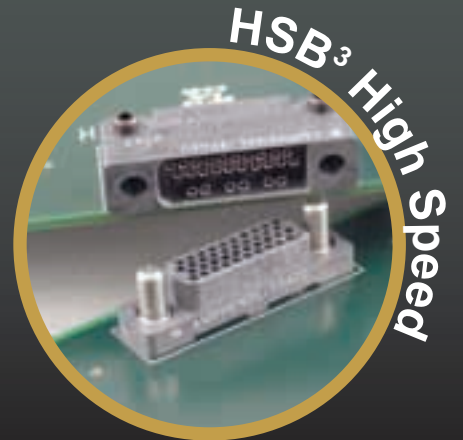
HDB<sup>3</sup> Mother Board Connector



HDB<sup>3</sup> I/O Connector



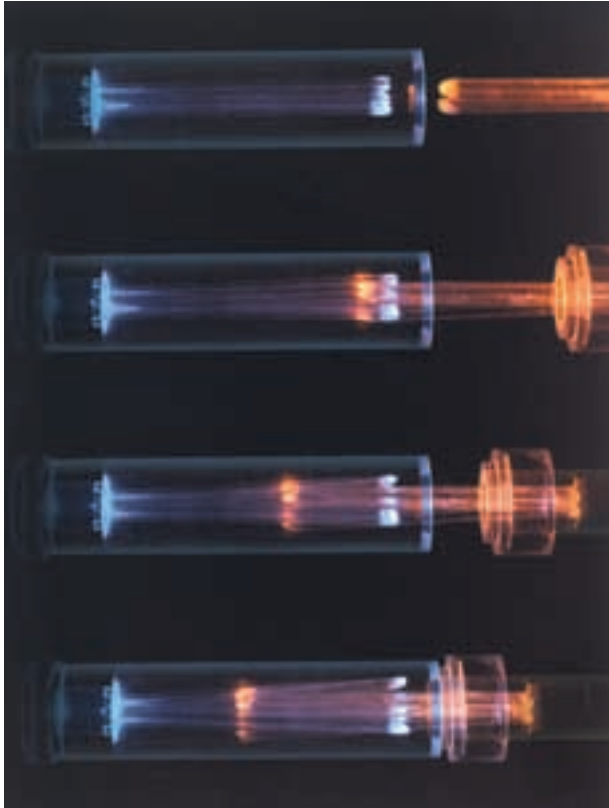
HDB<sup>3</sup> Stacker



HSB<sup>3</sup> High Speed

# HDB<sup>3</sup> AND HSB<sup>3</sup> FEATURES AND BENEFITS

## PERFORMANCE



## FEATURES

### FEATURES

Polarization:	“D” shaped design
Keying:	Optional keys offer 36 unique keying combinations
Guide Pins	Optional guide pins provide additional alignment
Radial Misalignment:	Capable of correcting up to a .020” initial radial misalignment
Angular Misalignment:	Capable of mating with up to a 2° initial angular misalignment

### CONNECTOR PERFORMANCE

Durability:	100,000 mating cycles
Insertion/Extraction Force:	1.5 ounce typical per contact
Operating Temperature:	-65° to 125°C
Current Rating:	2 amperes Hot swap 1 ampere maximum (load dependent)
Insulation Resistance:	5 gigaohms minimum Dielectric Withstanding
Voltage:	750 volts, 60 hertz, rms @ Sea Level 250 volts, 60 hertz, rms @ 70,000 feet Elevation
Solderability:	MIL-STD-202, Method 208
Salt Fog:	48 Hours IAW MIL-STD-1344, method 1001, test condition B
Humidity:	IAW MIL-STD-1344, method 1002, type II
Vibration:	4 hours in each of 3 mutually perpendicular axes IAW MIL-ST 1344, method 2005, test condition V, letter H
Shock:	1 shock along each of three mutually perpendicular axes IAW MIL-STD-1344, method 2004, test condition G
Data Rate (HSB <sup>3</sup> ):	Capable of 3.125 Gbps (consult Amphenol for arrangement)

## HDB<sup>3</sup> & HSB<sup>3</sup>



# HDB<sup>3</sup> MOTHER BOARD

## HDB<sup>3</sup> MOTHER BOARD – HOW TO ORDER

Mates with:

- Daughter Board
- I/O
- Stacker

Mother Board



Daughter Board

1.	2.	3.	4.	5.	6.
	Number of Contacts	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
<b>HDB-M4</b>	<b>-040</b>	<b>M</b>	<b>24</b>	<b>2</b>	<b>X</b>

### 1. Connector Type

#### HDB-M4

Designates HDB<sup>3</sup> Mother Board

### 2. Number of Contacts

	Number of Contacts	Dimension A	Dimension C
<b>040</b>	40	1.375	1.075
<b>060</b>	60	1.725	1.425
<b>080</b>	80	2.075	1.775
<b>120</b>	120	2.775	2.475
<b>160</b>	160	3.475	3.175

### 3. Brush Wire Plating

<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

### 4. Termination

	Type	Stickout (Dim. E)
<b>22</b>	PCB, Straight, .016 Dia	0.120
<b>23</b>	PCB, Straight, .016 Dia	0.150
<b>24</b>	PCB, Straight, .016 Dia	0.180
<b>26</b>	PCB, Straight, .016 Dia	0.240
<b>28</b>	PCB, Straight, .016 Dia	0.300

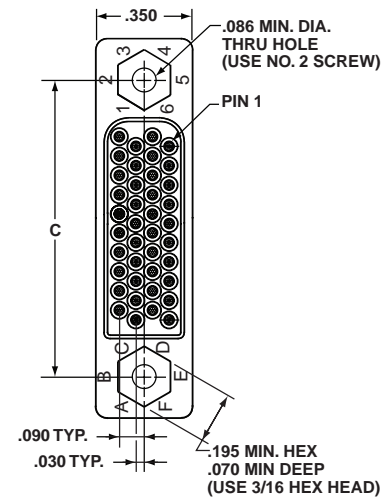
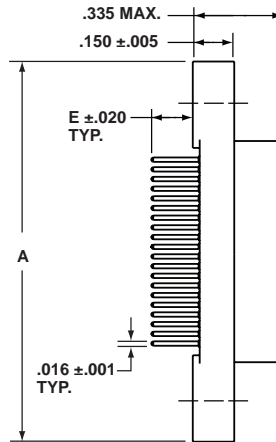
### 5. Contact Termination Finish

<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
<b>5</b>	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel
<b>6</b>	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper

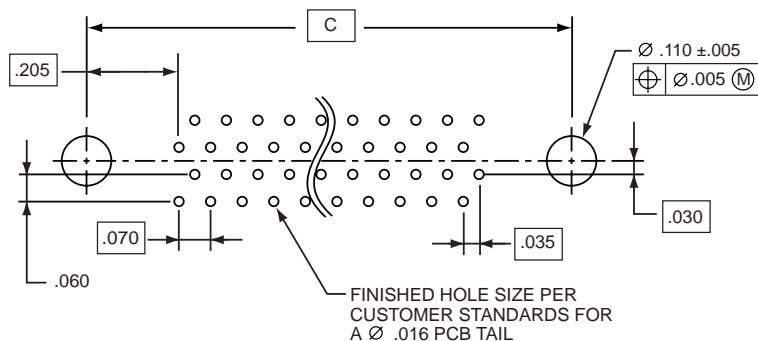
### 6. Hardware

**X** Less Hardware

Hardware is purchased separately (see page 11 for hardware options).



## MOTHER BOARD LAYOUT



# HDB<sup>3</sup> DAUGHTER BOARD

## HDB<sup>3</sup> DAUGHTER BOARD – HOW TO ORDER

Mates with:  
• Mother Board

### 1. Connector Type HDB-D4

Designates HDB<sup>3</sup> Daughter Board

### 2. Number of Contacts

	Number of Contacts	Dimension A	Dimension C
<b>040</b>	40	1.375	1.075
<b>060</b>	60	1.725	1.425
<b>080</b>	80	2.075	1.775
<b>120</b>	120	2.775	2.475
<b>160</b>	160	3.475	3.175

### 3. Brush Wire Plating

<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

### 4. Termination

	Type	Stickout (Dim. E)
<b>01</b>	PCB, Right Angle, .016 Dia.	0.090
<b>02</b>	PCB, Right Angle, .016 Dia.	0.120
<b>03</b>	PCB, Right Angle, .016 Dia.	0.150
<b>04</b>	PCB, Right Angle, .016 Dia.	0.180
<b>06</b>	PCB, Right Angle, .016 Dia.	0.300

### 5. Contact Termination Finish

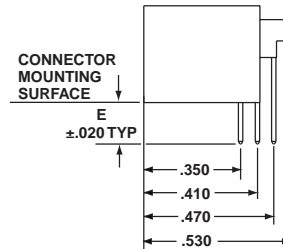
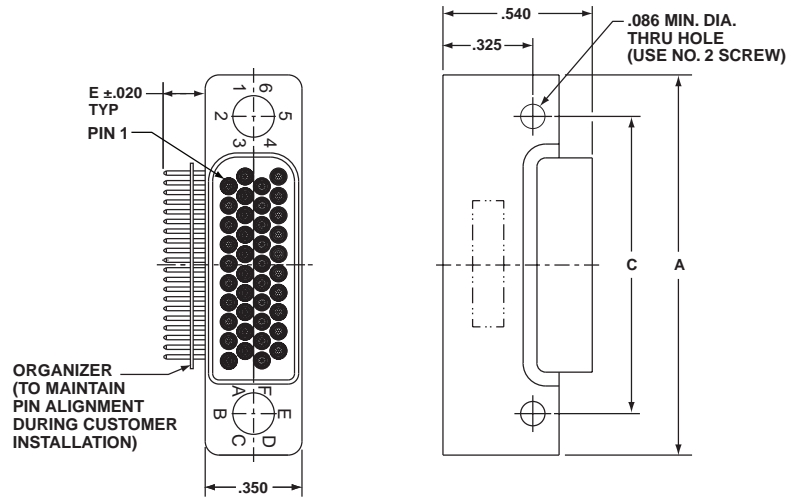
<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
<b>5</b>	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel
<b>6</b>	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper

### 6. Hardware

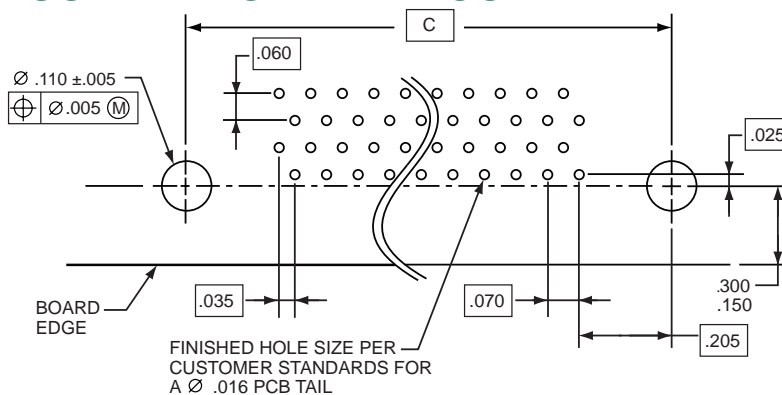
**X** Less Hardware

Hardware is purchased separately (see page 11 for hardware options).

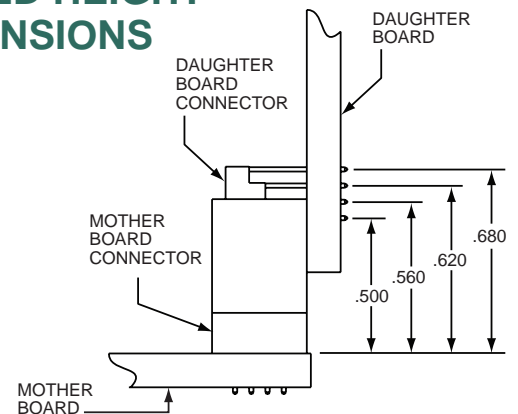
1.	2.	3.	4.	5.	6.
<b>HDB-D4</b>	<b>-040</b>	<b>M</b>	<b>01</b>	<b>2</b>	<b>X</b>



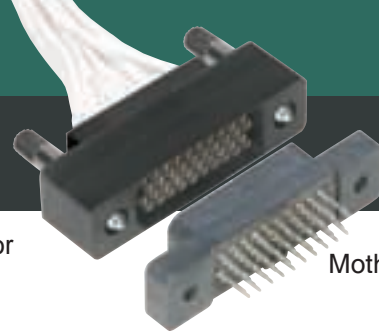
## DAUGHTER BOARD LAYOUT



## MATED HEIGHT DIMENSIONS



# HDB<sup>3</sup> I/O CONNECTOR



I/O Connector

Mother Board

## FEATURES/BENEFITS

- Cable to board applications
- Crimp termination
- Uses wire well size 22D

## HDB<sup>3</sup> I/O – HOW TO ORDER

Mates with:

- Standard Mother Board

### 1. Connector Type

#### HDB-D4C

Designates HDB<sup>3</sup> I/O Connector

### 2. Number of Contacts

Number of Contacts	Dimension A	Dimension C
<b>040</b>	1.375	1.075
<b>060</b>	1.725	1.425
<b>080</b>	2.075	1.775
<b>120</b>	2.775	2.475
<b>160</b>	3.475	3.175

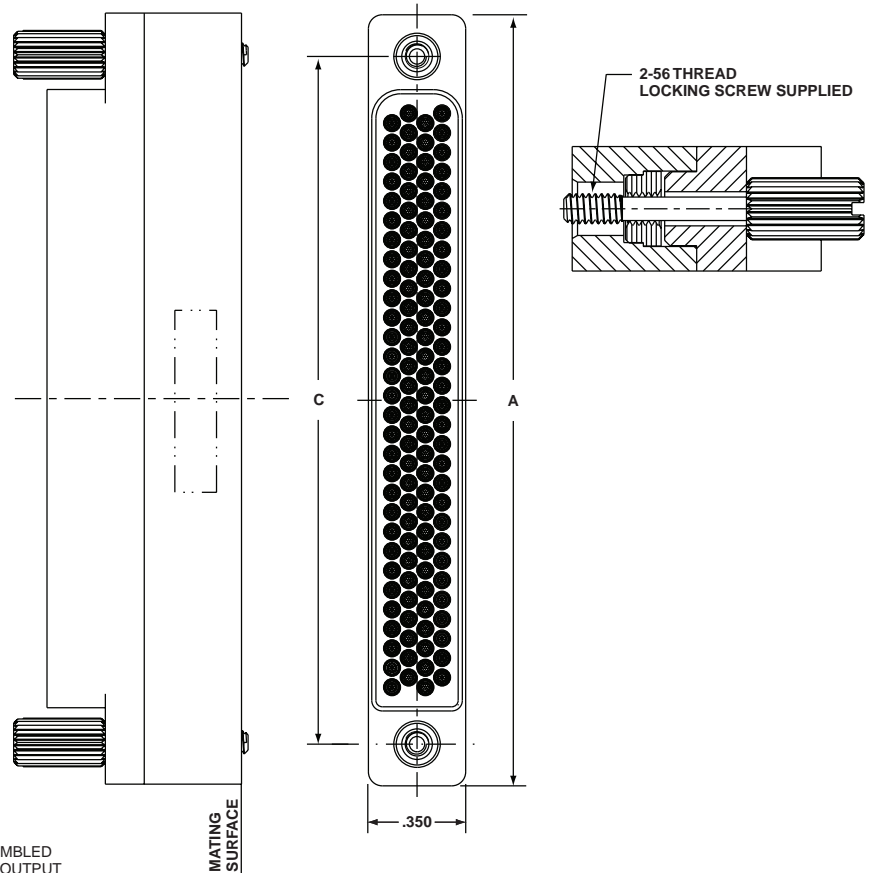
### 3. Brush Wire Plating

<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

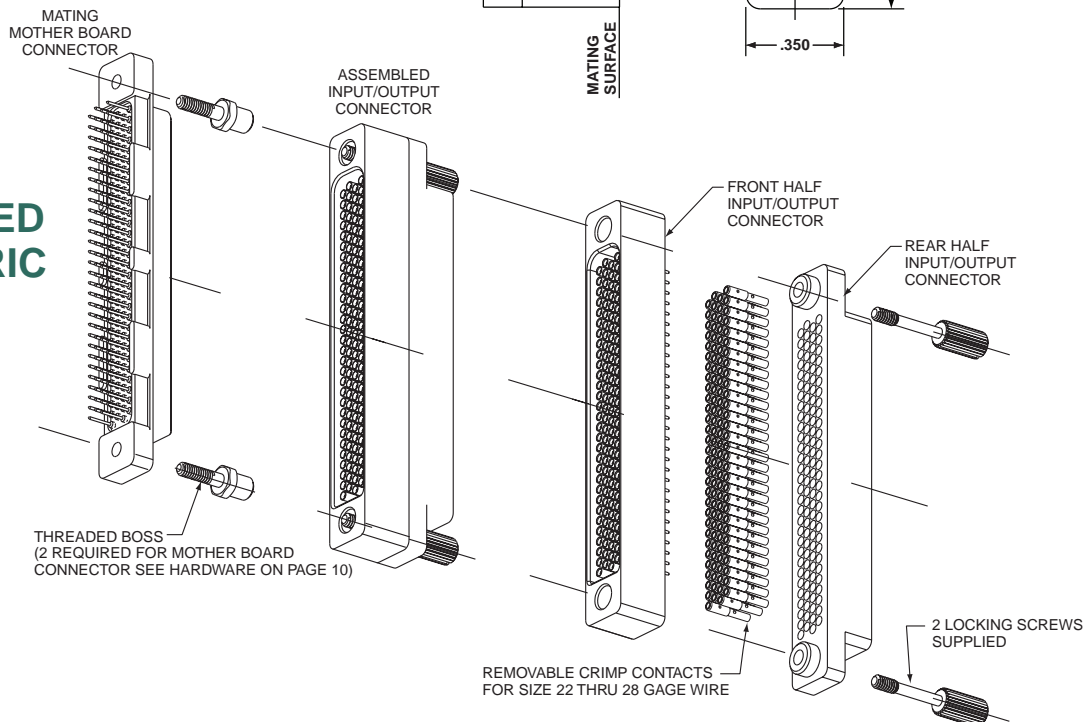
### 4. Contact Termination Finish

<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
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1.	2.	3.	4.
	Number of Contacts	Brush Wire Plating	Contact Termination Finish
<b>HDB-D4C</b>	<b>-120</b>	<b>C</b>	<b>2</b>

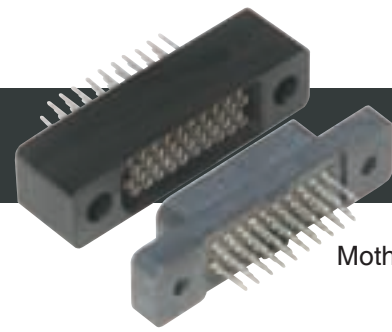


## EXPLODED ISOMETRIC VIEW





# HDB<sup>3</sup> STACKER CONNECTOR



Stacker

Mother Board

## FEATURES/BENEFITS

- For applications that need or demand parallel boards

## STACKER CONNECTOR – HOW TO ORDER

Mates with:

- Standard Mother Board

### 1. Connector Type

#### HDB-D4S

Designates HDB<sup>3</sup> Stacker Connector

### 2. Number of Contacts

Number Diff Signals	Number of Contacts	Dimension A	Dimension C
<b>040</b>	40	1.375	1.075
<b>060</b>	60	1.725	1.425
<b>080</b>	80	2.075	1.775
<b>120</b>	120	2.775	2.475
<b>160</b>	160	3.475	3.175

### 3. Brush Wire Plating

<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

### 4. Termination

Type	Stickout (Dim. E)
<b>22</b> PCB, Straight, .016 Dia	0.100
<b>23</b> PCB, Straight, .016 Dia	0.130
<b>24</b> PCB, Straight, .016 Dia	0.160
<b>28</b> PCB, Straight, .016 Dia	0.280

### 5. Contact Termination Finish

<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
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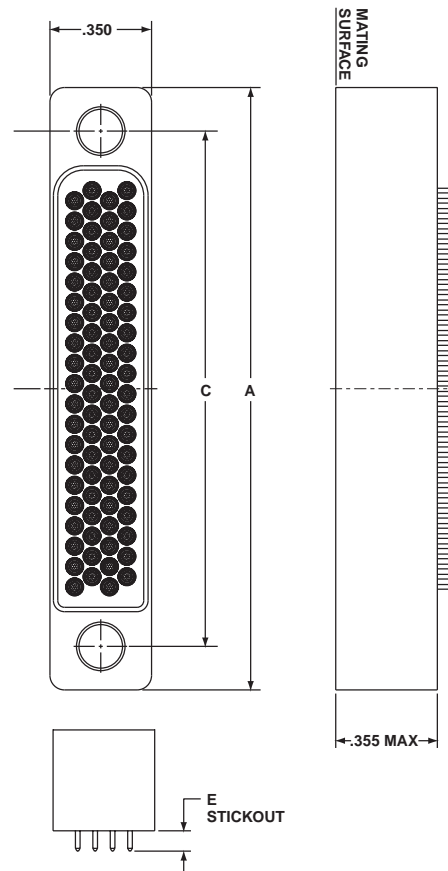


### 6. Hardware

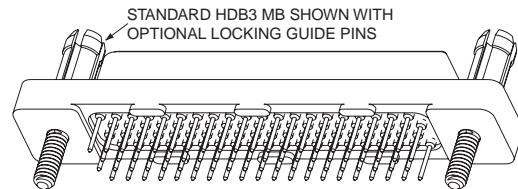
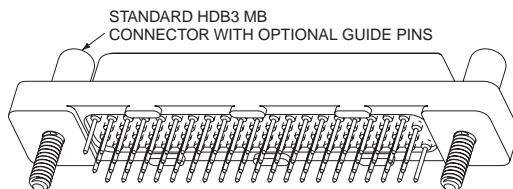
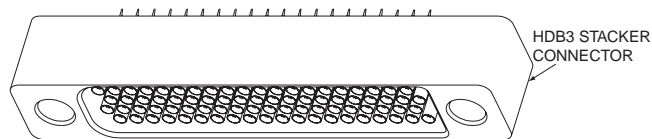
<b>X</b>	Less Hardware
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Hardware is purchased separately (see page 11 for hardware options).

1.	2.	3.	4.	5.	6.
	Number of Contacts	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
<b>HDB-D4S</b>	<b>-120</b>	<b>C</b>	<b>22</b>	<b>2</b>	<b>X</b>



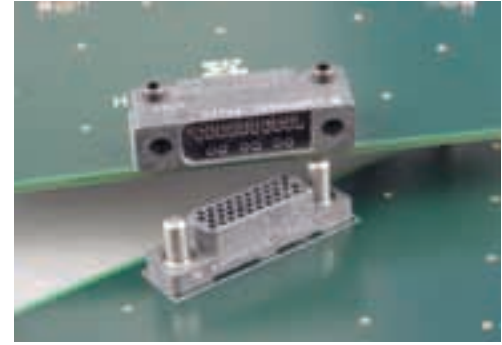
## EXPLODED ISOMETRIC VIEW



# HIGH SPEED BRUSH (HSB<sup>3</sup>) SERIES 3.125 Gb/s

## BENEFITS

- High speed configuration available that allows data rates up to 3.125 Gb/s via 100 ohm matched impedance differential pairs
  - Partially populated standard HDB<sup>3</sup> mother board & daughter board bodies
- Contact a Sales Engineer for validation results



## MOTHER BOARD – HOW TO ORDER

Mates with:

- High Speed Daughter Board

	1.	2.	3.	4.	5.	6.	7.
		Number of Differential Pairs	Differential Signal	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
<b>HSB-M4</b>		<b>-03</b>	<b>D</b>	<b>M</b>	<b>24</b>	<b>2</b>	<b>X</b>

### 1. Connector Type

#### HSB-M4

Designates High Speed HSB<sup>3</sup> Mother Board

### 2. Number of Contacts

Number Differential Pairs	No. Low Speed Signals	Dimension A	Dimension C
<b>03</b>	20	1.375	1.075
<b>05</b>	30	1.725	1.425
<b>07</b>	40	2.075	1.775
<b>10</b>	60	2.775	2.475
<b>13</b>	80	3.475	3.175

### 3. Differential Signal

<b>D</b>	Standard
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### 4. Brush Wire Plating

<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

### 5. Termination

	Type	Stickout (Dim. E)
<b>22</b>	PCB, Straight, .016 Dia	0.120
<b>23</b>	PCB, Straight, .016 Dia	0.150
<b>24</b>	PCB, Straight, .016 Dia	0.180
<b>26</b>	PCB, Straight, .016 Dia	0.240
<b>28</b>	PCB, Straight, .016 Dia	0.300

### 6. Contact Termination Finish

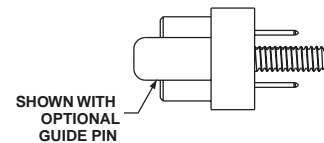
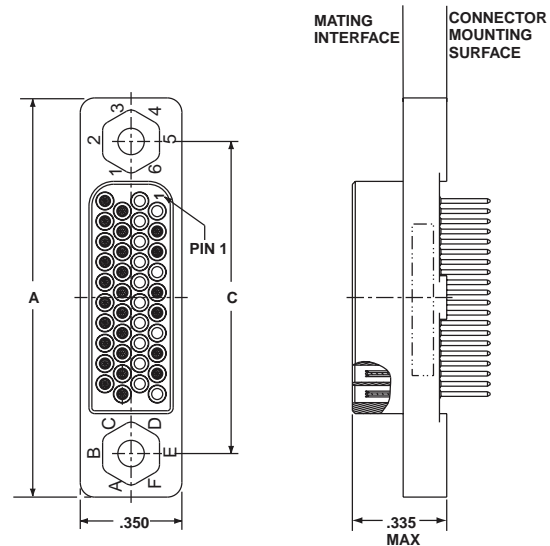
<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
<b>5</b>	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel
<b>6</b>	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper



### 7. Hardware

<b>X</b>	Less Hardware
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Hardware is purchased separately (see page 11 for hardware options).



# HIGH SPEED BRUSH (HSB<sup>3</sup>) SERIES 3.125 Gb/s

## DAUGHTER BOARD – HOW TO ORDER

Mates with:

- High Speed Mother Board

1.	2.	3.	4.	5.	6.	7.
	Number of Differential Pairs	Differential Signals	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
<b>HSB-D4</b>	<b>-03</b>	<b>D</b>	<b>M</b>	<b>02</b>	<b>2</b>	<b>X</b>

### 1. Connector Type

#### HSB-D4

Designates High Speed HSB<sup>3</sup> Daughter Board

### 2. Number of Contacts

Number Diff Pairs	No. Low Speed Signals	Dimension A	Dimension D
<b>03</b>	20	1.375	1.075
<b>05</b>	30	1.725	1.425
<b>07</b>	40	2.075	1.775
<b>10</b>	60	2.775	2.475
<b>13</b>	80	3.475	3.175

### 3. Differential Signals

<b>D</b>	Standard
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### 4. Brush Wire Plating

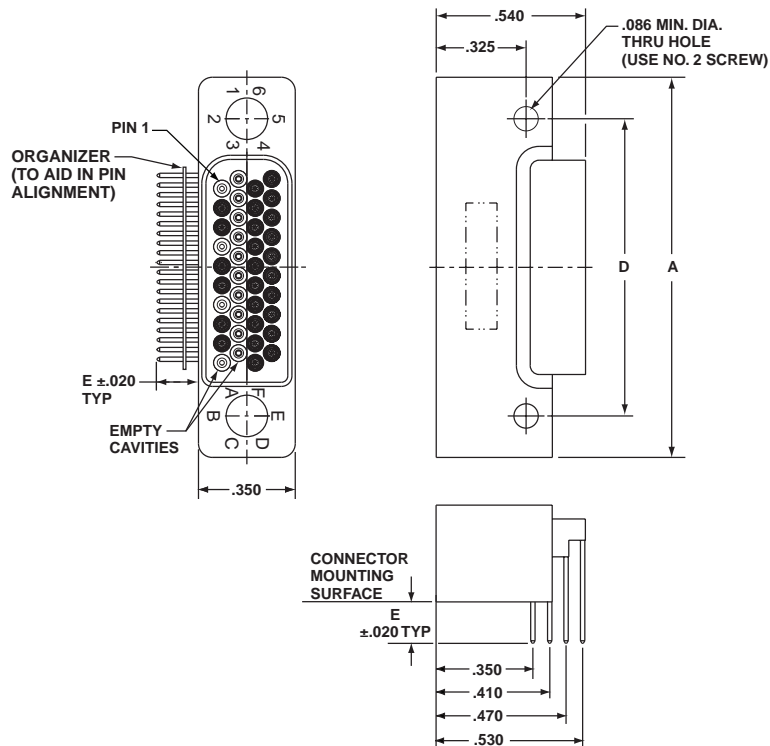
<b>M</b>	0.000050 Au Min. thick over Nickel
<b>C</b>	0.000020 Au Min. thick over Nickel

### 5. Termination

	Type	Stickout (Dim. E)
<b>01</b>	PCB, Right Angle, .016 Dia	0.090
<b>02</b>	PCB, Right Angle, .016 Dia	0.120
<b>03</b>	PCB, Right Angle, .016 Dia	0.150
<b>04</b>	PCB, Right Angle, .016 Dia	0.180
<b>06</b>	PCB, Right Angle, .016 Dia	0.300

### 6. Contact Termination Finish

<b>2</b>	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel
<b>5</b>	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel
<b>6</b>	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper



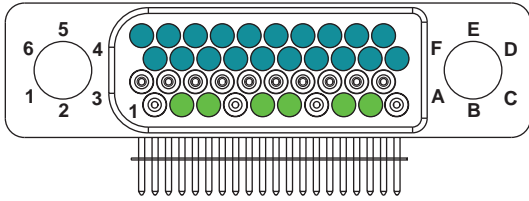
### 7. Hardware

<b>X</b>	Less Hardware
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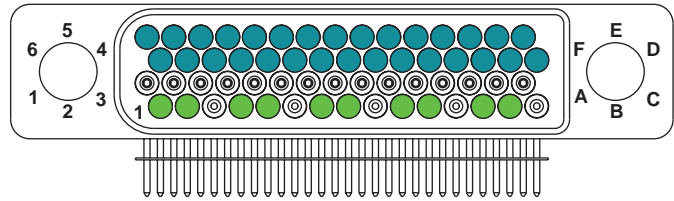
Hardware is purchased separately (see page 11 for hardware options).

# HSB<sup>3</sup> LAYOUT

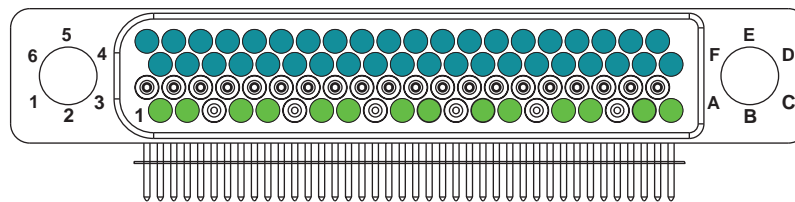
## HSB<sup>3</sup> ARRANGEMENTS



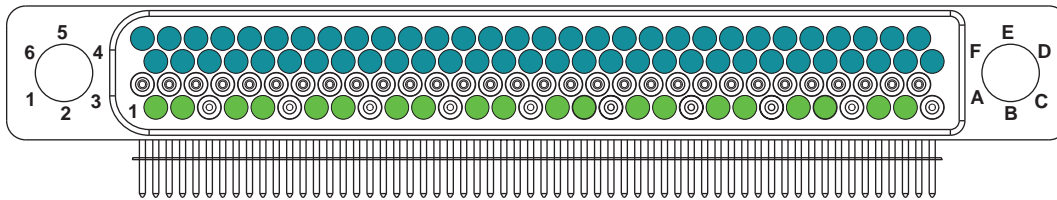
40 Pin Body with 3 Differential Pair, 20 Signal Contacts



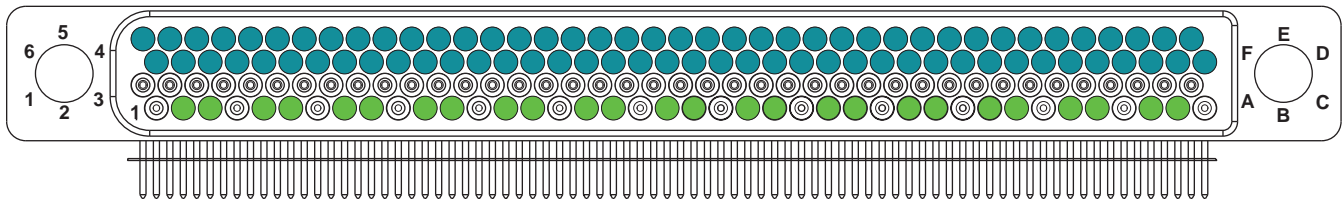
60 Pin Body with 5 Differential Pair, 30 Signal Contacts



80 Pin Body with 7 Differential Pair, 40 Signal Contacts







120 Pin Body with 10 Differential Pair, 60 Signal Contacts



160 Pin Body with 13 Differential Pair, 80 Signal Contacts

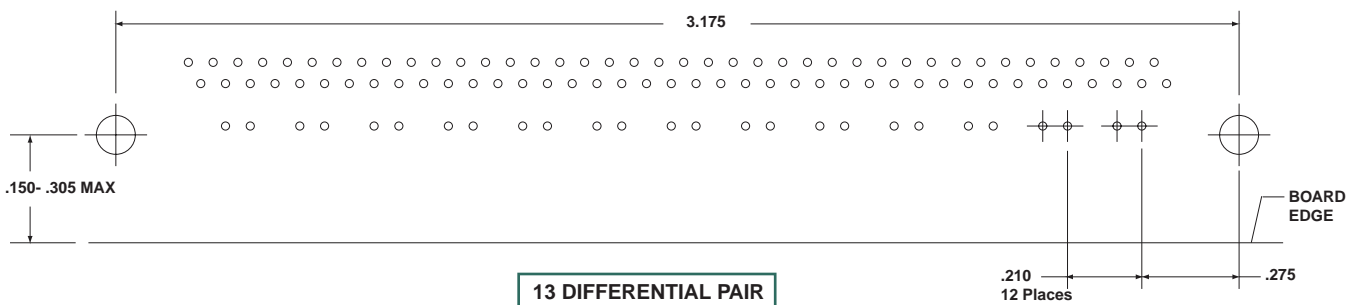
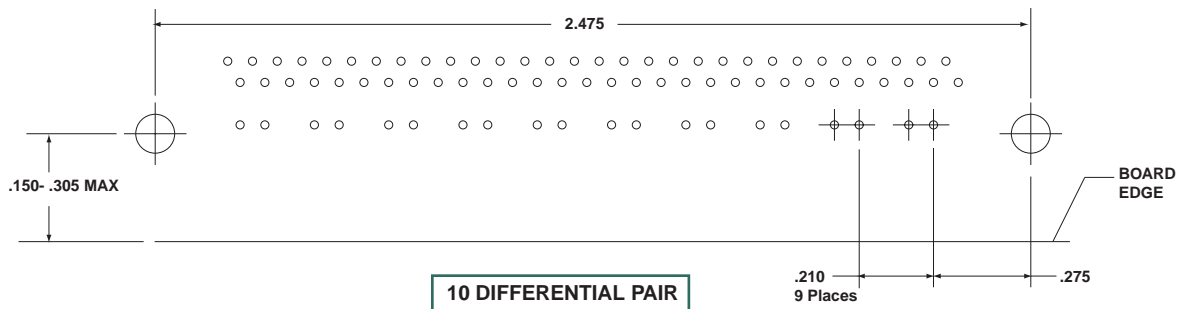
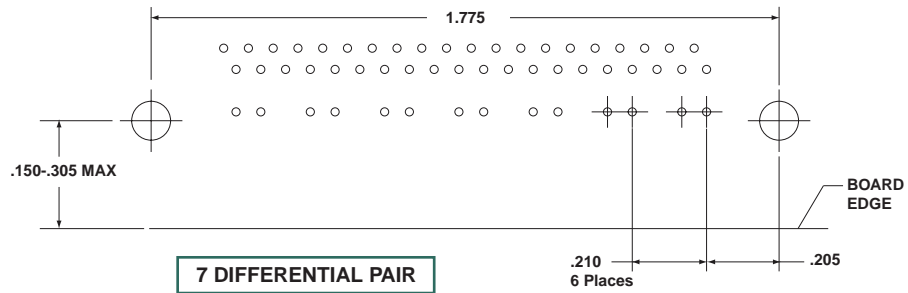
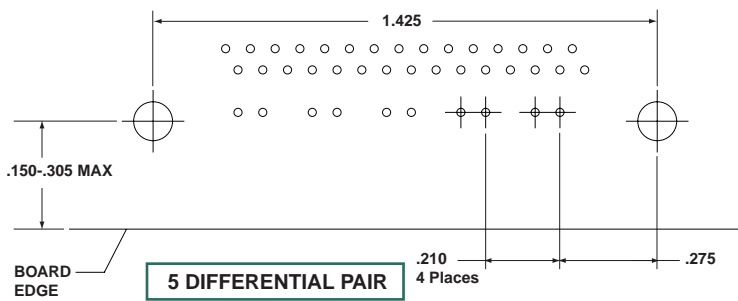
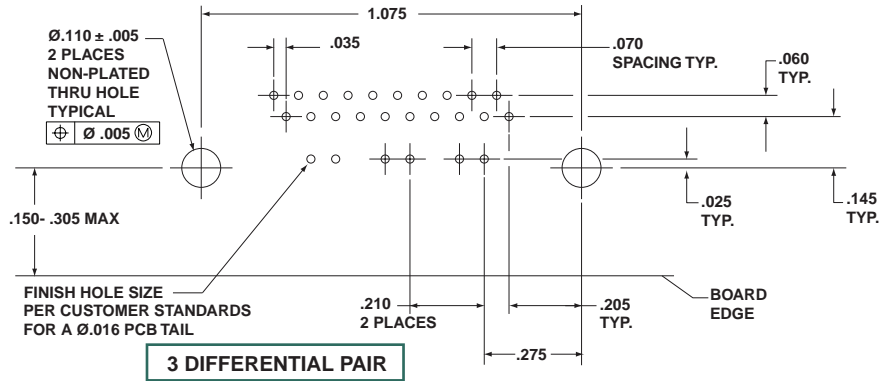
As viewed from front of daughter board connector

### KEY

-   100 Ohm Differential Pair Contacts  
(100 Ohm Differential contact pairs capable of 3.125 Gb/s data rates)
-  Empty Contact Cavity
-  Standard Digital, Low Speed Signal Contacts

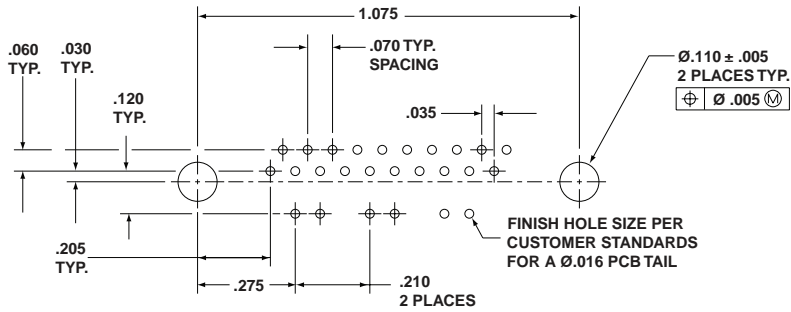
# HSB<sup>3</sup> RECOMMENDED BOARD LAYOUT

## DAUGHTER BOARD

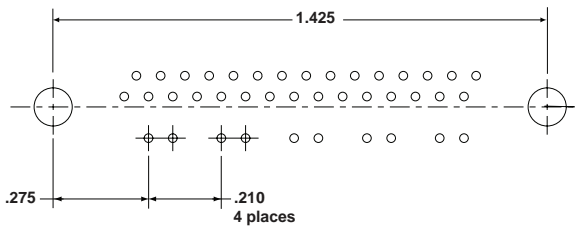


# HSB<sup>3</sup> RECOMMENDED BOARD LAYOUT

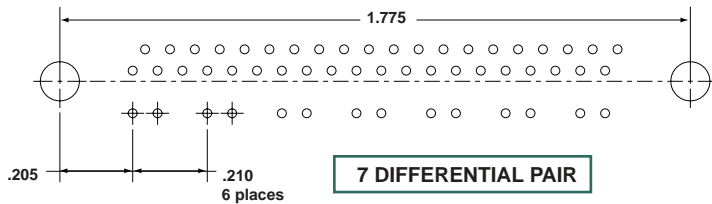
## MOTHER BOARD



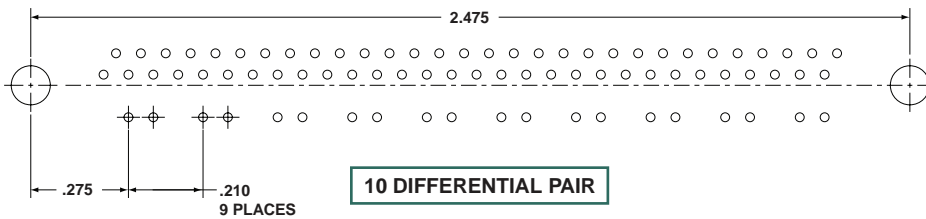
**3 DIFFERENTIAL PAIR**



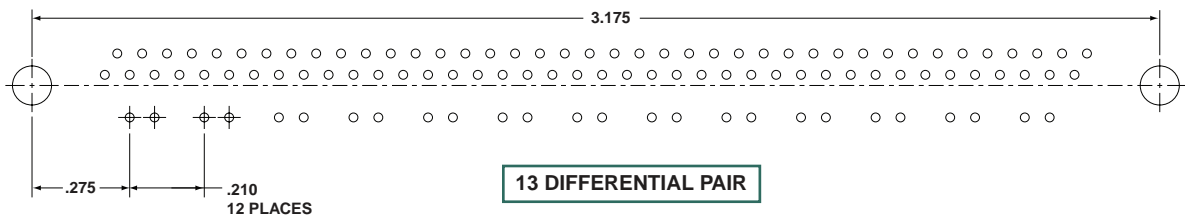
**5 DIFFERENTIAL PAIR**



**7 DIFFERENTIAL PAIR**



**10 DIFFERENTIAL PAIR**

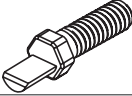
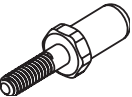
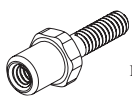
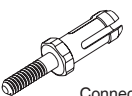


**13 DIFFERENTIAL PAIR**

# HARDWARE FOR HDB<sup>3</sup> AND HSB<sup>3</sup> CONNECTORS

## HARDWARE FOR ALL CONFIGURATIONS (Sold Separately)

### MOTHER BOARD



PART NUMBER	TYPE	STICKOUT	
HDB-508803-001	POLARIZATION KEY (QTY 2)	0.250	
HDB-508803-002	POLARIZATION KEY (QTY 2)	0.500	
HDB-508803-003	POLARIZATION KEY (QTY 2)	0.750	
HDB-508802-001	GUIDE PIN (QTY 2)	0.250	
HDB-508802-002	GUIDE PIN (QTY 2)	0.500	
HDB-508802-003	GUIDE PIN (QTY 2)	0.750	
HDB-508808-000	THREADED BOSS (QTY 2)*	0.250	
HDB-508808-001	THREADED BOSS (QTY 2)*	0.500	
HDB-508808-002	THREADED BOSS (QTY 2)*	0.750	
HDB-508808-020	LOCKING GUIDE PIN (QTY 2)	0.250	
HDB-508808-021	LOCKING GUIDE PIN (QTY 2)	0.500	
HDB-508808-022	LOCKING GUIDE PIN (QTY 2)	0.750	

Accepts I/O Connector Jack Screw

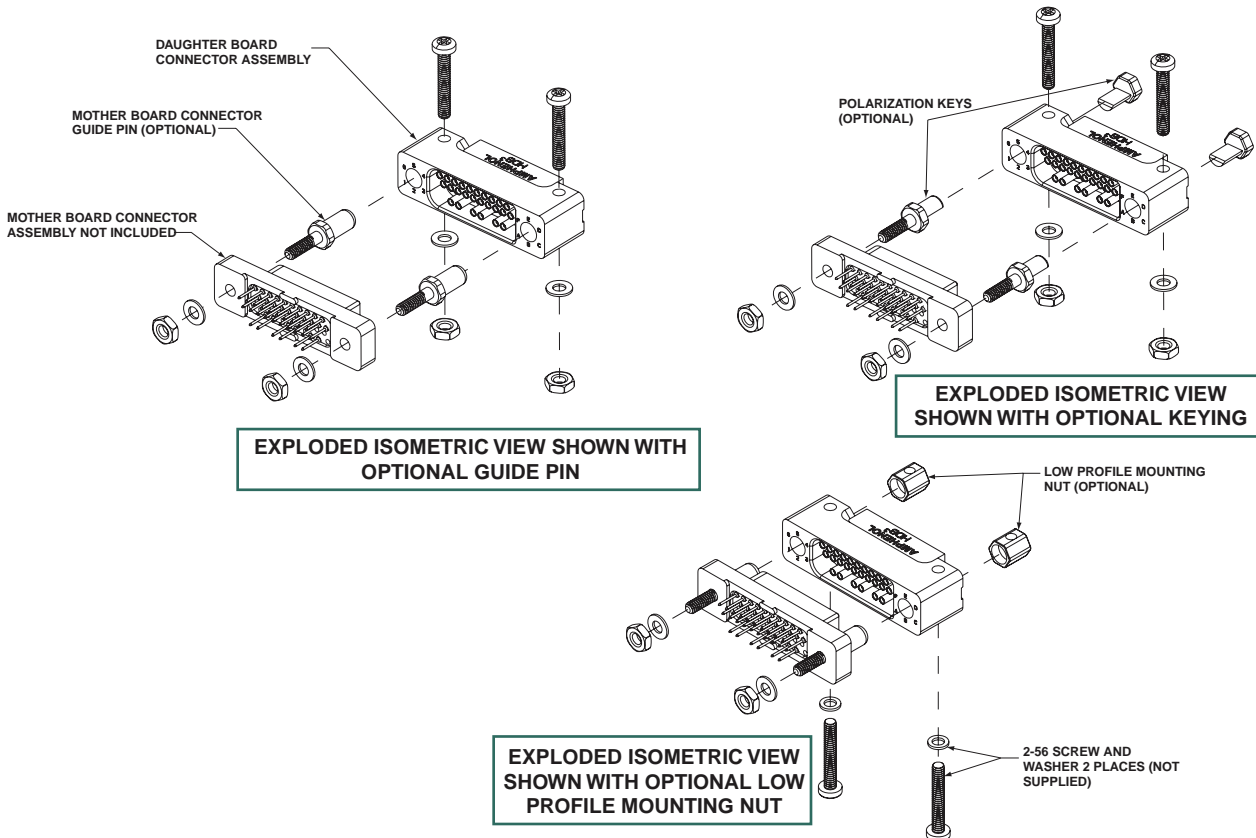
Shown with Mother Board Connector on page 5

\* Required with Mother Board only when mating to I/O Connector

### DAUGHTER BOARD

PART NUMBER	TYPE	
HDB-508804-000	POLARIZATION KEY (QTY 2)	
HDB-508804-001	LOW PROFILE MOUNTING NUT (QTY 2)	

## EXPLODED ISOMETRIC VIEW

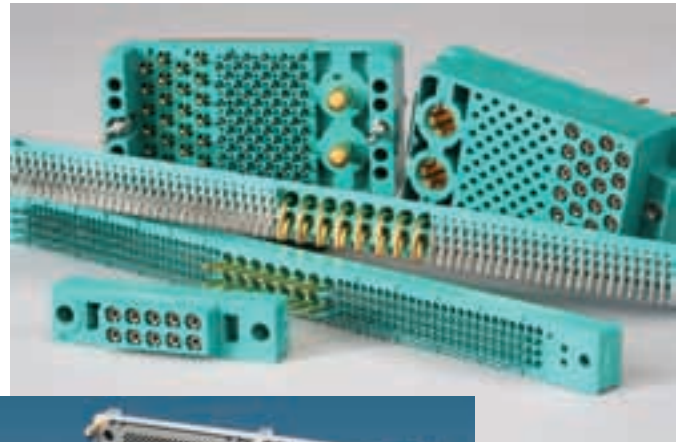


# OTHER AMPHENOL RECTANGULAR PRODUCTS

## MIL-DTL-55302 BRUSH CONTACT TECHNOLOGY

Amphenol Bristle Brush Contact:  
Multiple Strands of High Tensile Strength Wires Bundled  
Together, Providing Superior Electrical  
Connection with Low Mating Force

See Amphenol Catalog, 12-035, Low Mating Force Rectangular  
Connectors, currently on-line at [www.amphenol-aerospace.com](http://www.amphenol-aerospace.com).\*



## HIGH PERFORMANCE LINE REPLACEABLE MODULE (LRM)

Amphenol LRM Surface Mount Connectors meet the  
high density needs of today's integrated electronic  
modules. Design versatility and product reliability makes  
Amphenol the premier choice for the system designer in  
solving board interconnect requirements.

See Amphenol Catalog, 12-037, LRM Interconnect Products, currently  
on-line at [www.amphenol-aerospace.com](http://www.amphenol-aerospace.com).\*



## GIGASTAK & DIGASTAK HIGH SPEED RECTANGULARS

New family of high speed LRM connectors that are  
capable of achieving data rates in excess of 6.25 Gpbs  
via 100 ohm matched impedance differential pairs. Each  
insert arrangement has been optimized through strategic  
placement of signal and ground contacts for the perfect  
balance of impedance control and cross talk mitigation  
for a given data rate. This series also offers a unique  
solderless termination to module cards via Amphenol  
Intercon's cStack technology.

Consult Amphenol Aerospace for further information.



## MEDICAL CABLE CONNECTORS



- Utilize high performance B<sup>3</sup> brush contact
- 10 contacts per connector
- Plug – crimp removable contacts
- Receptacle – printed circuit board contacts
- Currently available in 12 colors, each with a unique keying combination (plug only, user is to provide key hole for receptacle)
- Also offered as partially populated
- Notches in plug connector to assist with over molding

For more information see Amphenol Catalog, 12-035, Low Mating Force  
Rectangular Connectors, currently on-line at [www.amphenol-aerospace.com](http://www.amphenol-aerospace.com).\*

\* Amphenol Aerospace will be providing a Combined Rectangular Products catalog, 12-R1, which will combine the products covered in 12-035, 12-037, the HDB3 and HSB3 product covered in this catalog, along with other Amphenol Rectangular interconnect products. Ask for the new combined Amphenol Rectangular Interconnect Products catalog; available Jan. 2011.